

Material Content Data Sheet

RoHS

Sales Product Name	SPU01N60C3	**Issued**	11. December 2019
MA#	MA000798122		
Package	PG-TO251-3-341	**Weight***	380.56 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.893	0.23	0.23	2347	2347
leadframe	inorganic material	phosphorus	7723-14-0	0.075	0.02		196	
	non noble metal	iron	7439-89-6	0.248	0.07		653	
	non noble metal	copper	7440-50-8	248.124	65.20	65.29	652002	652851
wire	non noble metal	aluminium	7429-90-5	0.449	0.12	0.12	1179	1179
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.753	0.46		4606	
	plastics	brominated resin	-	1.878	0.49		4935	
	organic material	carbon black	1333-86-4	2.003	0.53		5264	
	plastics	epoxy resin	-	16.902	4.44		44413	
	inorganic material	silicondioxide	60676-86-0	102.663	26.98	32.90	269769	328987
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9828	9828
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1337	1337
solder	non noble metal	tin	7440-31-5	0.026	0.01		69	
	noble metal	silver	7440-22-4	0.033	0.01		87	
	non noble metal	lead	7439-92-1	1.262	0.33	0.35	3315	3471
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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